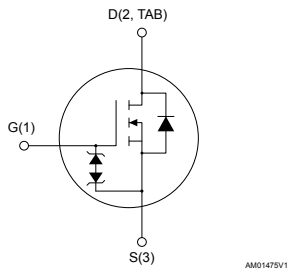
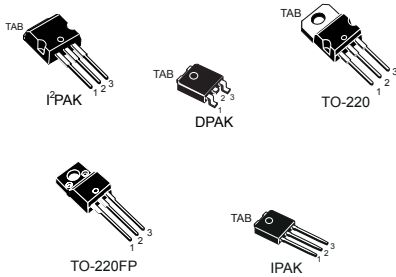


## N-channel 500 V, 1.22 $\Omega$ typ., 4.4 A SuperMESH™ Power MOSFETs in I<sup>2</sup>PAK, DPAK, TO-220, TO-220FP and IPAK packages



### Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	Package
STB5NK50Z-1	500 V	1.5 $\Omega$	4.4 A	I <sup>2</sup> PAK
STD5NK50ZT4				DPAK
STP5NK50Z				TO-220
STP5NK50ZFP				TO-220FP
STU5NK50Z				IPAK

- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitance
- Zener-protected

### Applications

- Switching applications

### Description

These high-voltage devices are Zener-protected N-channel Power MOSFETs developed using the SuperMESH™ technology by STMicroelectronics, an optimization of the well-established PowerMESH™. In addition to a significant reduction in on-resistance, these devices are designed to ensure a high level of dv/dt capability for the most demanding applications.

#### Product status link

[STB5NK50Z-1](#)
[STD5NK50ZT4](#)
[STP5NK50Z](#)
[STP5NK50ZFP](#)
[STU5NK50Z](#)

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		I <sup>2</sup> PAK, DPAK, TO-220, IPAK	TO-220FP	
V <sub>DS</sub>	Drain-source voltage	500		V
V <sub>GS</sub>	Gate-source voltage	±30		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	4.4	4.4 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	2.7	2.7 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	17.6	17.6 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	70	25	W
ESD	Gate-source human body model (R = 1.5 kΩ, C = 100 pF)	3		kV
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat-sink (t = 1 s, T <sub>C</sub> = 25 °C)		2.5	kV
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	4.5		V/ns
T <sub>j</sub>	Operating junction temperature range	-55 to 150		°C
T <sub>stg</sub>	Storage temperature range			

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 4.4$  A,  $di/dt \leq 200$  A/μs,  $V_{DD} \leq V_{(BR)DSS}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value				Unit
		I <sup>2</sup> PAK, TO-220	TO-220FP	DPAK	IPAK	
R <sub>thj-case</sub>	Thermal resistance junction-case	1.78	5	1.78		°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient	62.5			100	°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb			50		°C/W

1. When mounted on an 1-inch<sup>2</sup> FR-4, 2oz Cu board.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>j</sub> Max)	4.4	A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	130	mJ

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$	500			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 500\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 500\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 50\text{ }\mu\text{A}$	3	3.75	4.5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 2.2\text{ A}$		1.22	1.5	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	535		$\mu\text{F}$
$C_{oss}$	Output capacitance			75		
$C_{rSS}$	Reverse transfer capacitance			17		
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }400\text{ V}$ , $V_{GS} = 0\text{ V}$	-	45		$\mu\text{F}$
$Q_g$	Total gate charge	$V_{DD} = 400\text{ V}$ , $I_D = 4.4\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 16. Test circuit for gate charge behavior)	-	20	28	nC
$Q_{gs}$	Gate-source charge			4		
$Q_{gd}$	Gate-drain charge			10		

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250\text{ V}$ , $I_D = 2.2\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ (see Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	15	-	ns
$t_r$	Rise time			10		
$t_{d(off)}$	Turn-off delay time			32		
$t_f$	Fall time			15		

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		4.4	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				17.6	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 4.4 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 4.4 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	-	310		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 30 \text{ V}, T_j = 150^\circ\text{C}$ (see Figure 17. Test circuit for inductive load switching and diode recovery times)		1.425		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			9.2		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

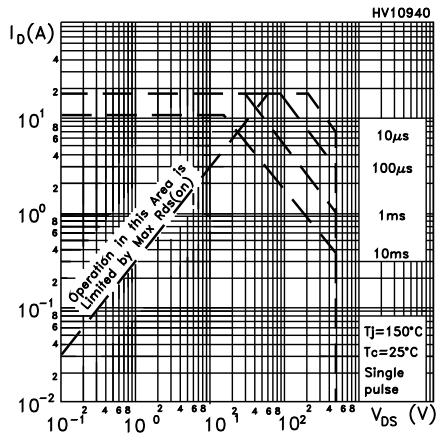
**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0 \text{ A}$	$\pm 30$	-	-	V

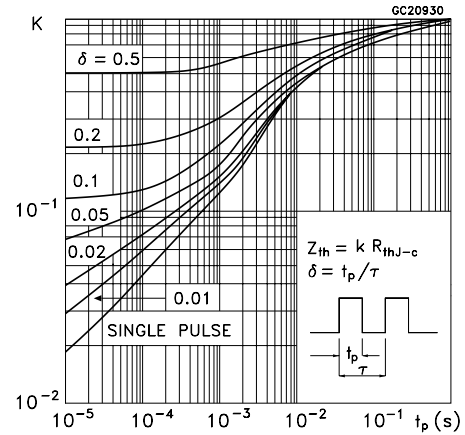
The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

## 2.1 Electrical characteristics curves

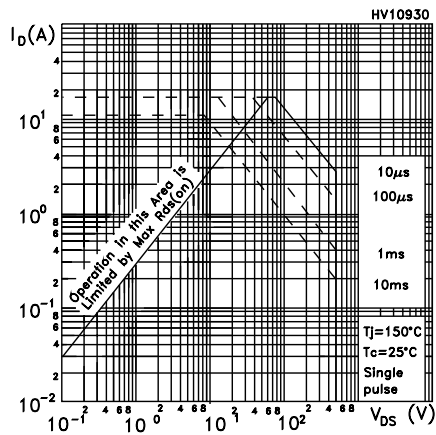
**Figure 1. Safe operating area for I<sup>2</sup>PAK, DPAK, TO-220, IPAK**



**Figure 2. Thermal impedance for I<sup>2</sup>PAK, DPAK, TO-220, IPAK**



**Figure 3. Safe operating area for TO-220FP**



**Figure 4. Thermal impedance for TO-220FP**

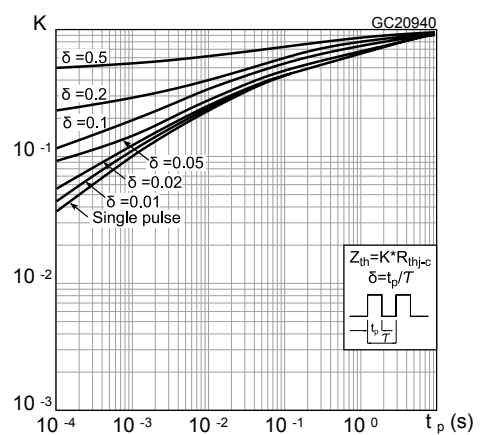


Figure 5. Output characteristics

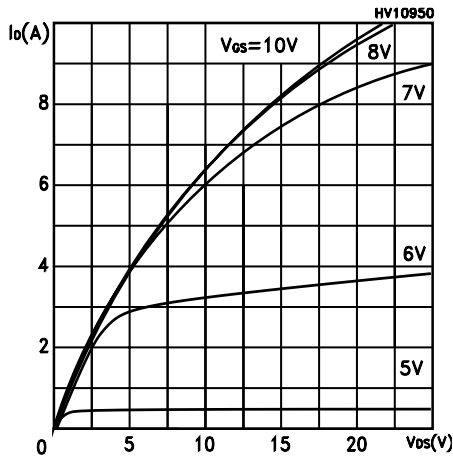


Figure 6. Transfer characteristics

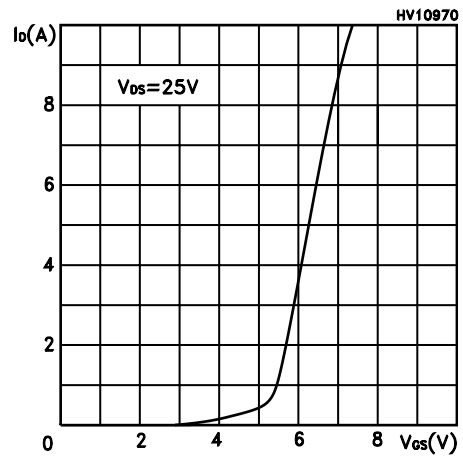


Figure 7. Static drain-source on resistance

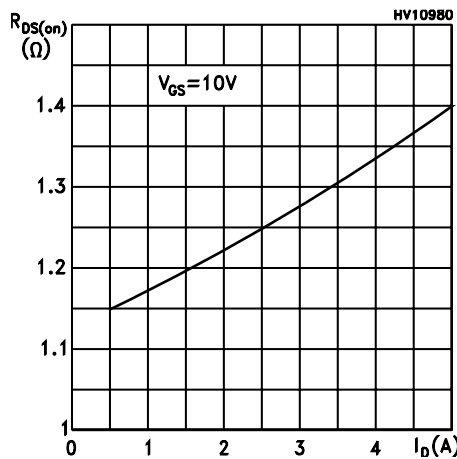


Figure 8. Gate charge vs gate-source voltage

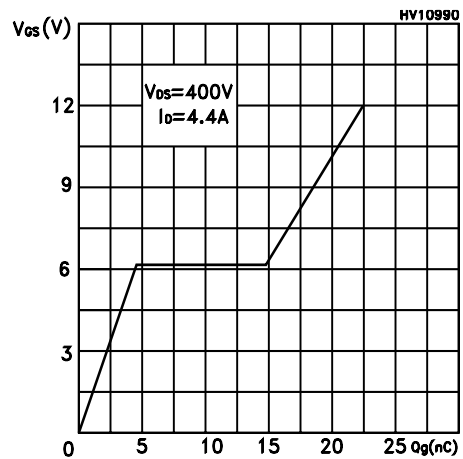


Figure 9. Capacitance variations

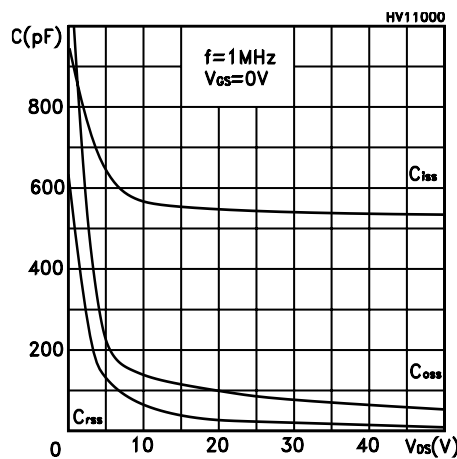


Figure 10. Normalized gate threshold voltage vs temperature

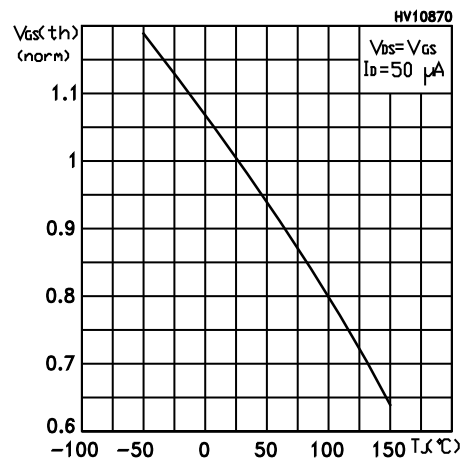


Figure 11. Normalized on resistance vs temperature

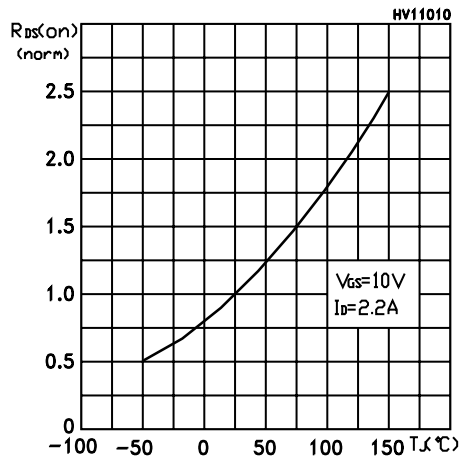


Figure 12. Source-drain diode forward characteristic

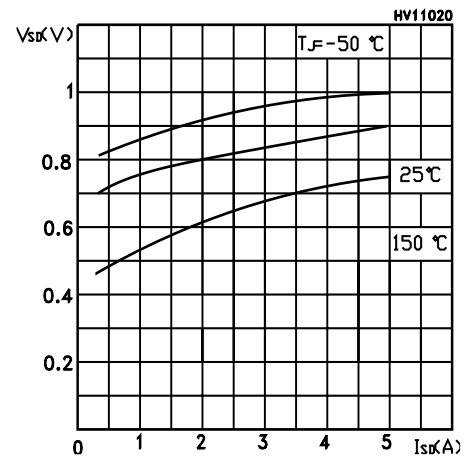


Figure 13. Normalized  $V_{(BR)DSS}$  vs temperature

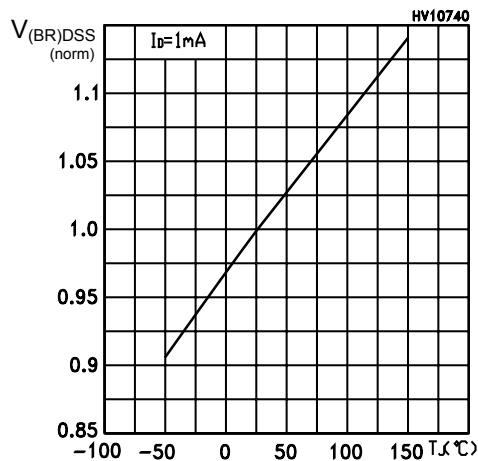
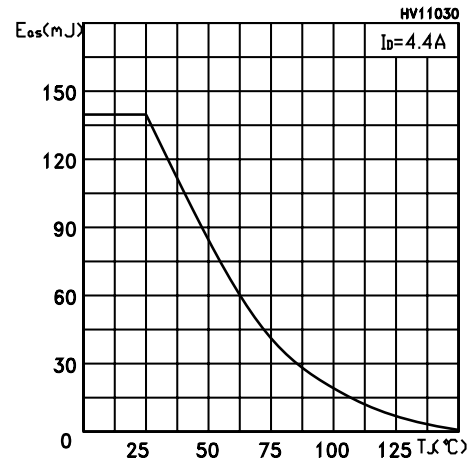
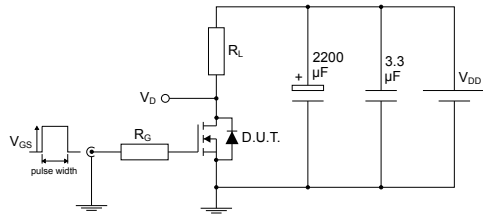


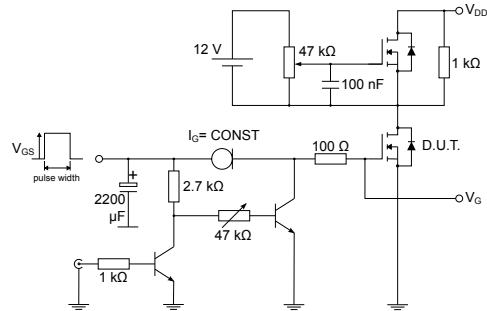
Figure 14. Maximum avalanche energy vs temperature



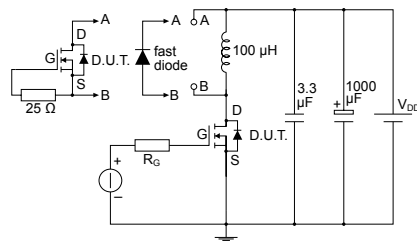
### 3 Test circuits

**Figure 15. Test circuit for resistive load switching times**


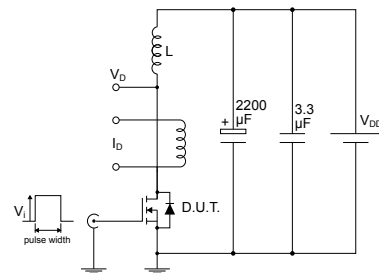
AM01468v1

**Figure 16. Test circuit for gate charge behavior**


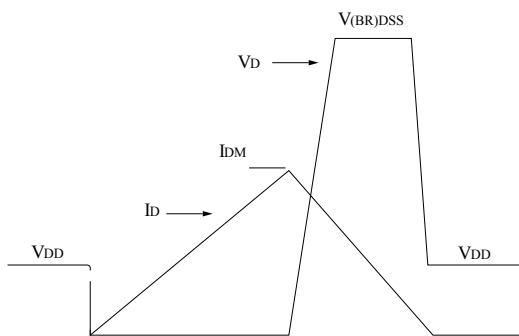
AM01469v1

**Figure 17. Test circuit for inductive load switching and diode recovery times**


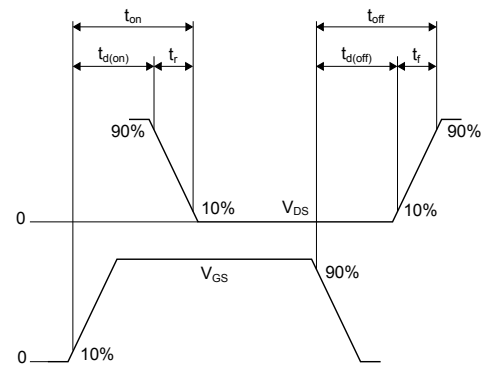
AM01470v1

**Figure 18. Unclamped inductive load test circuit**


AM01471v1

**Figure 19. Unclamped inductive waveform**


AM01472v1

**Figure 20. Switching time waveform**


AM01473v1





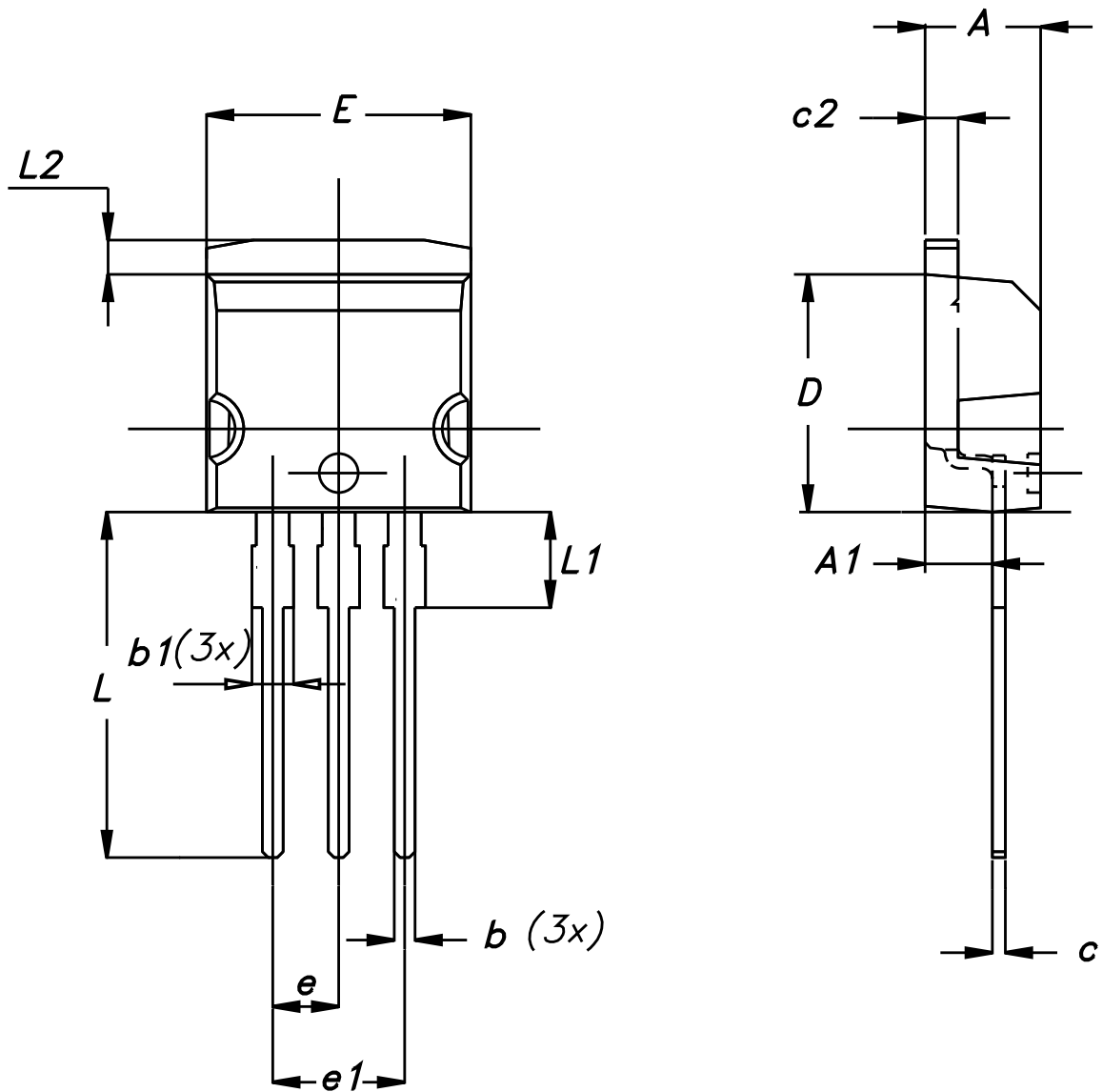
## 4 Package information

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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

4.1 I<sup>2</sup>PAK package information

Figure 21. I<sup>2</sup>PAK package outline



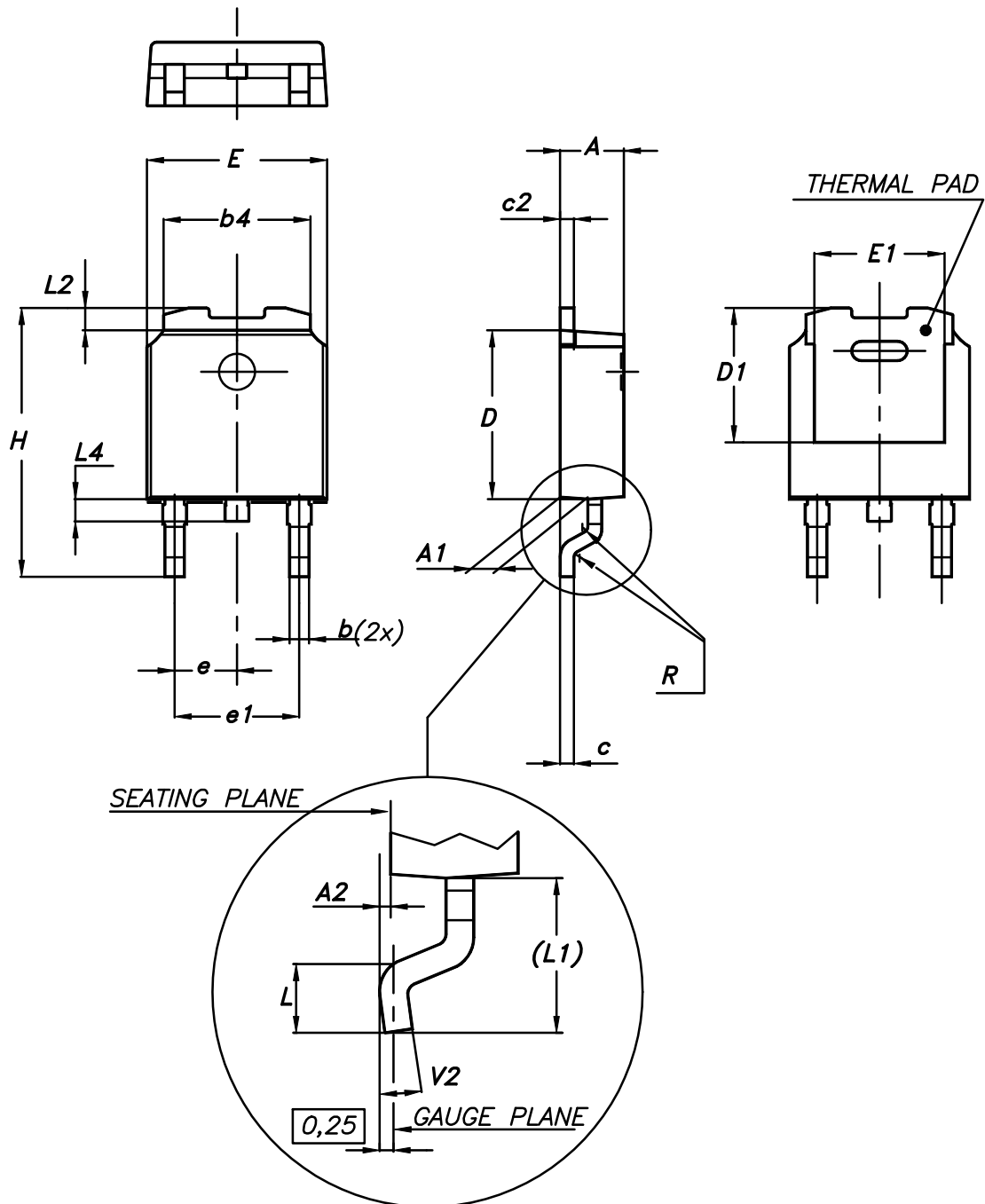
0004982\_Rev\_H

**Table 9. I<sup>2</sup>PAK package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40	-	4.60
A1	2.40	-	2.72
b	0.61	-	0.88
b1	1.14	-	1.70
c	0.49	-	0.70
c2	1.23	-	1.32
D	8.95	-	9.35
e	2.40	-	2.70
e1	4.95	-	5.15
E	10	-	10.40
L	13	-	14
L1	3.50	-	3.93
L2	1.27	-	1.40

## 4.2 DPAK (TO-252) type A package information

Figure 22. DPAK (TO-252) type A package outline



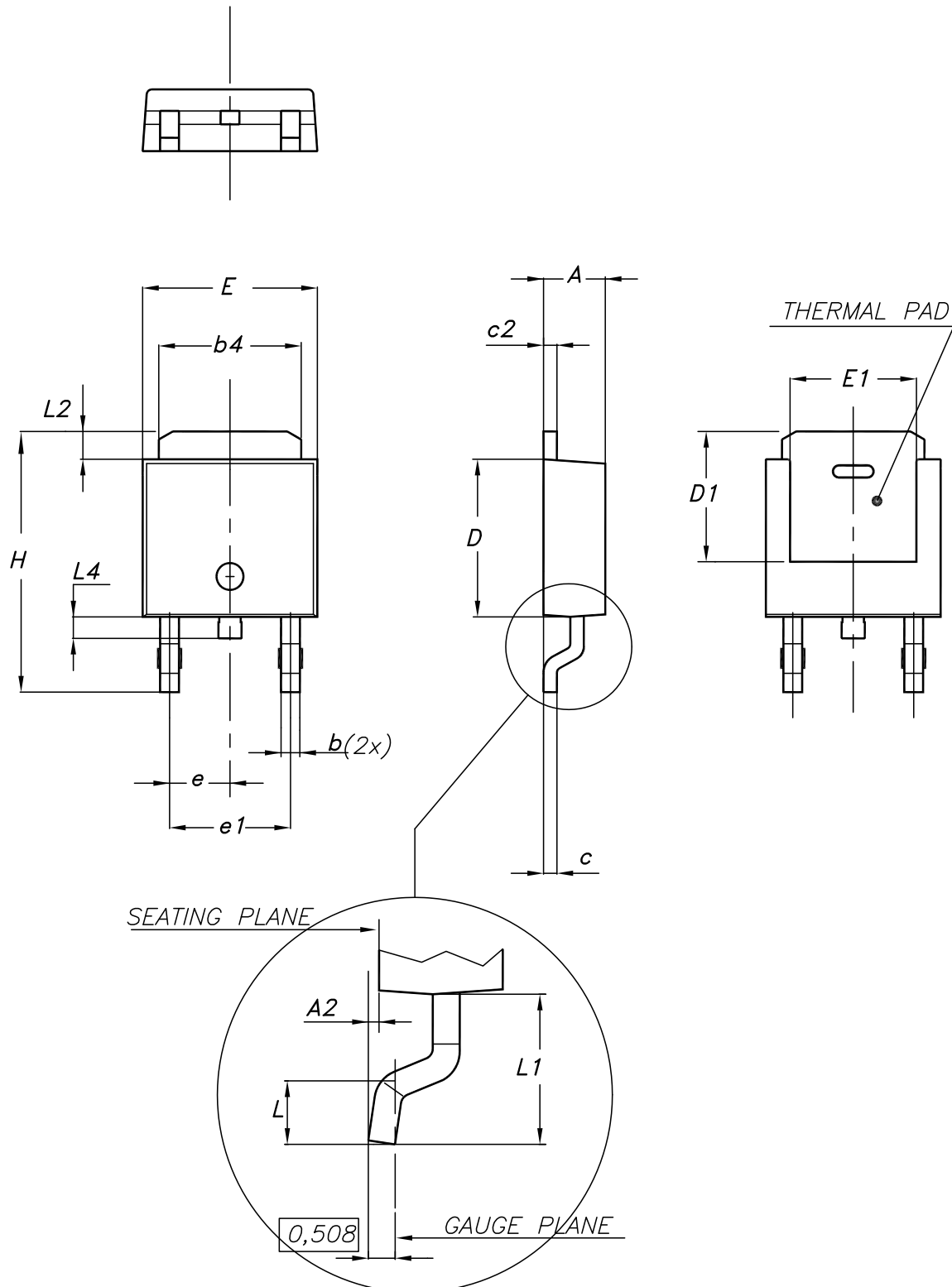
0068772\_A\_25

**Table 10. DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

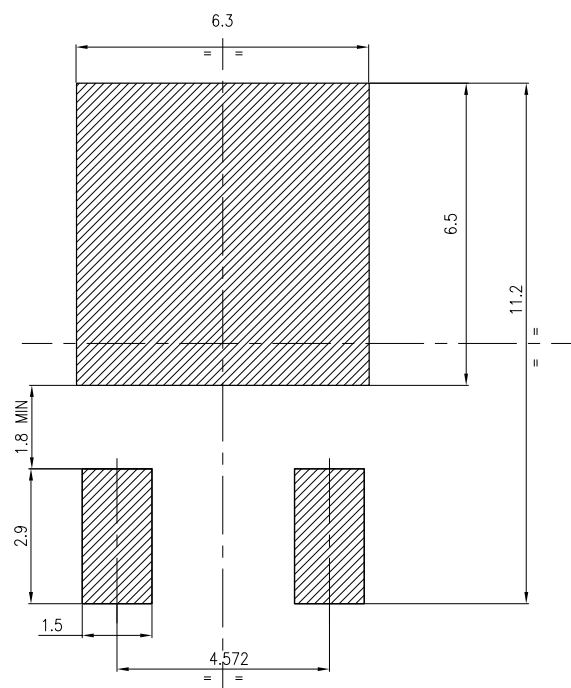
### 4.3 DPAK (TO-252) type E package information

Figure 23. DPAK (TO-252) type E package outline



**Table 11. DPAK (TO-252) type E mechanical data**

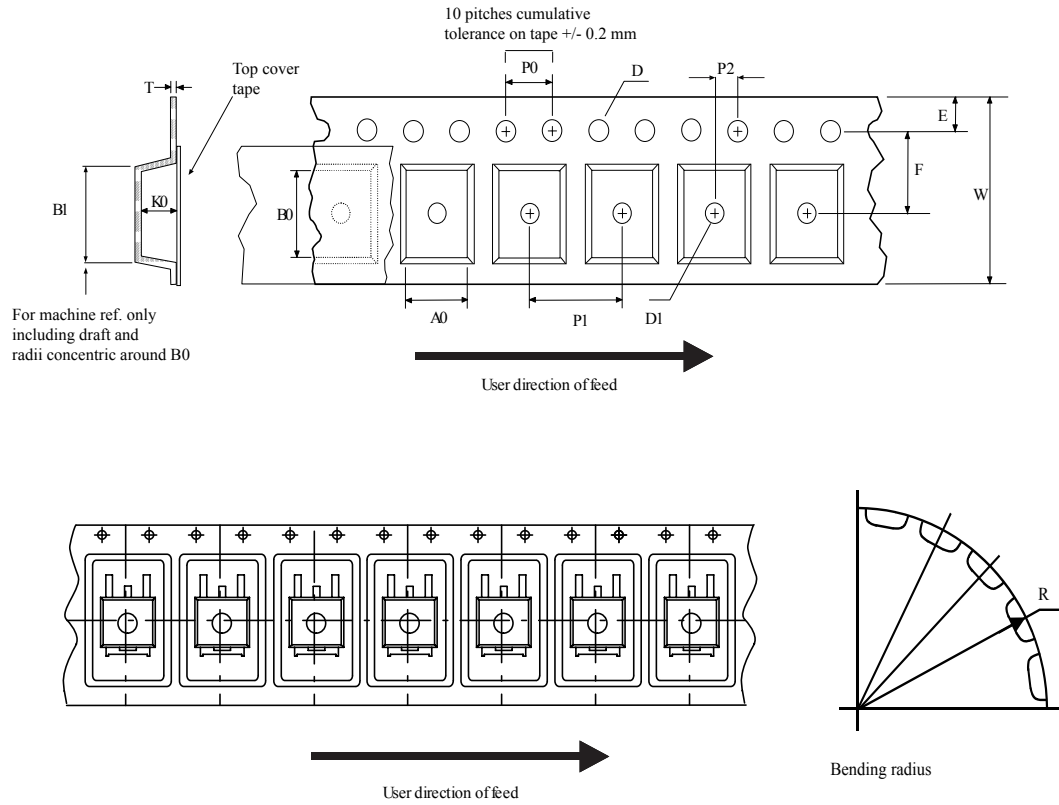
Dim.	mm		
	Min.	Typ.	Max.
A	2.18		2.39
A2			0.13
b	0.65		0.884
b4	4.95		5.46
c	0.46		0.61
c2	0.46		0.60
D	5.97		6.22
D1	5.21		
E	6.35		6.73
E1	4.32		
e		2.286	
e1		4.572	
H	9.94		10.34
L	1.50		1.78
L1		2.74	
L2	0.89		1.27
L4			1.02

**Figure 24. DPAK (TO-252) recommended footprint (dimensions are in mm)**


FP\_0068772\_25

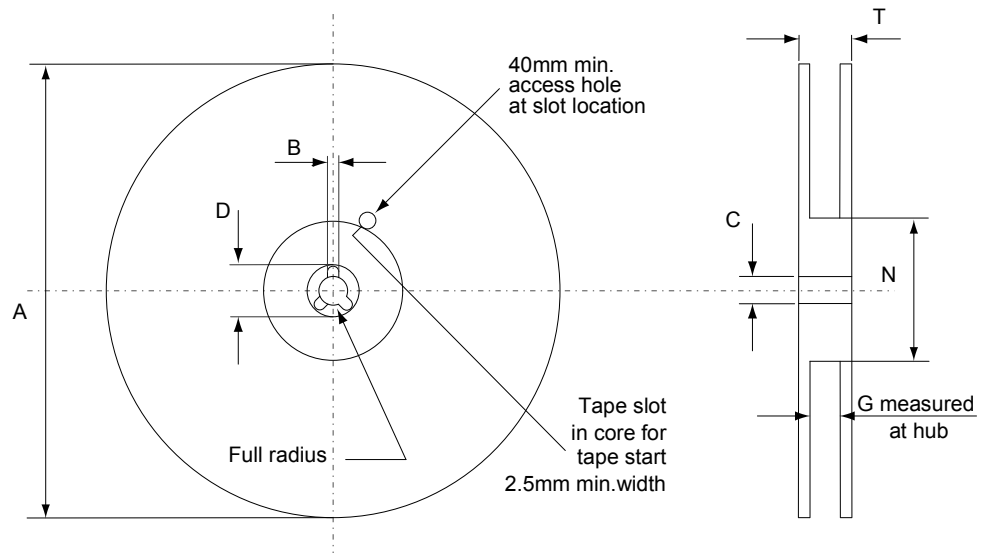
#### 4.4 DPAK (TO-252) packing information

Figure 25. DPAK (TO-252) tape outline



AM08852v1



**Figure 26. DPAK (TO-252) reel outline**


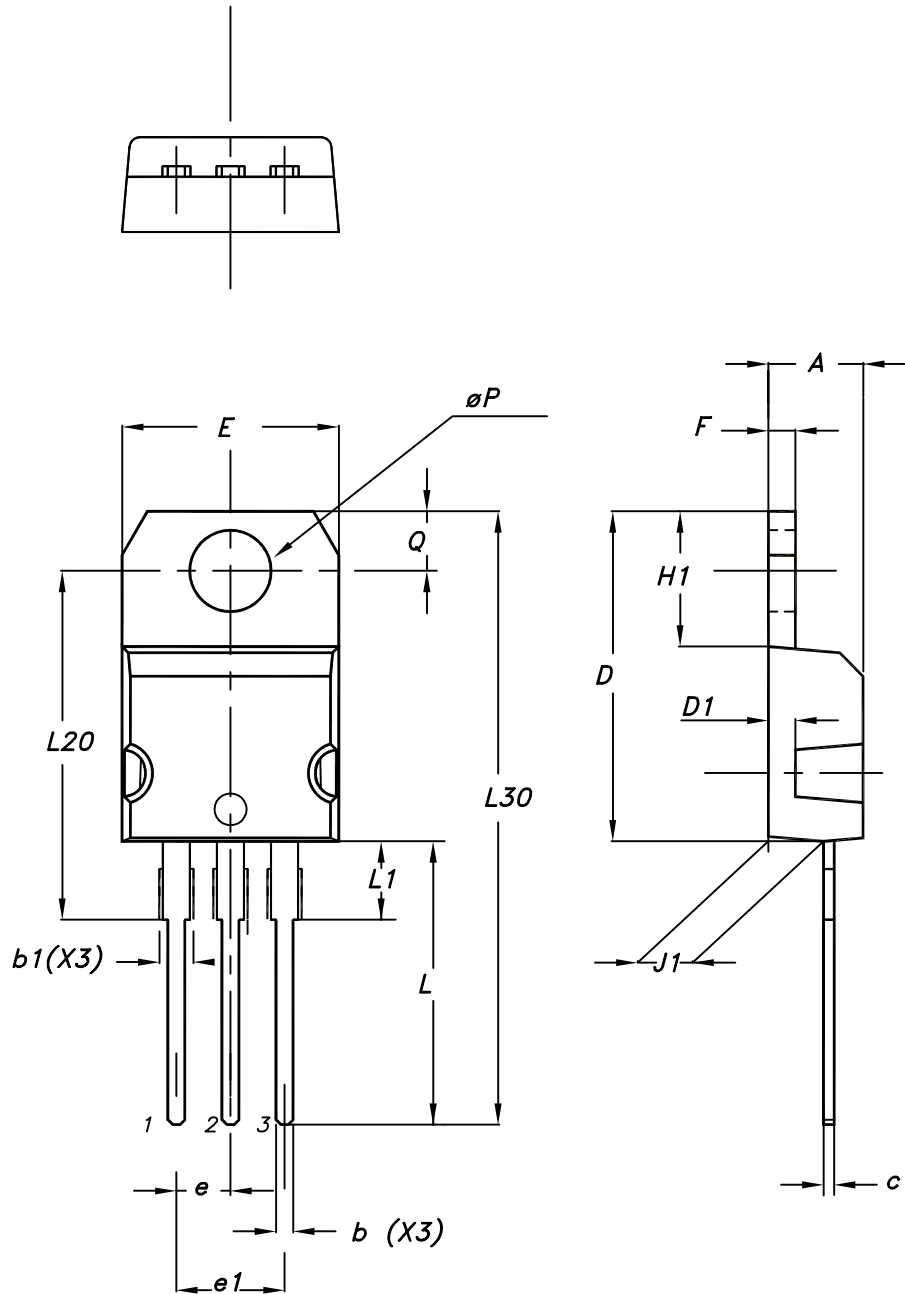
AM06038v1

**Table 12. DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

### 4.5 TO-220 type A package information

Figure 27. TO-220 type A package outline



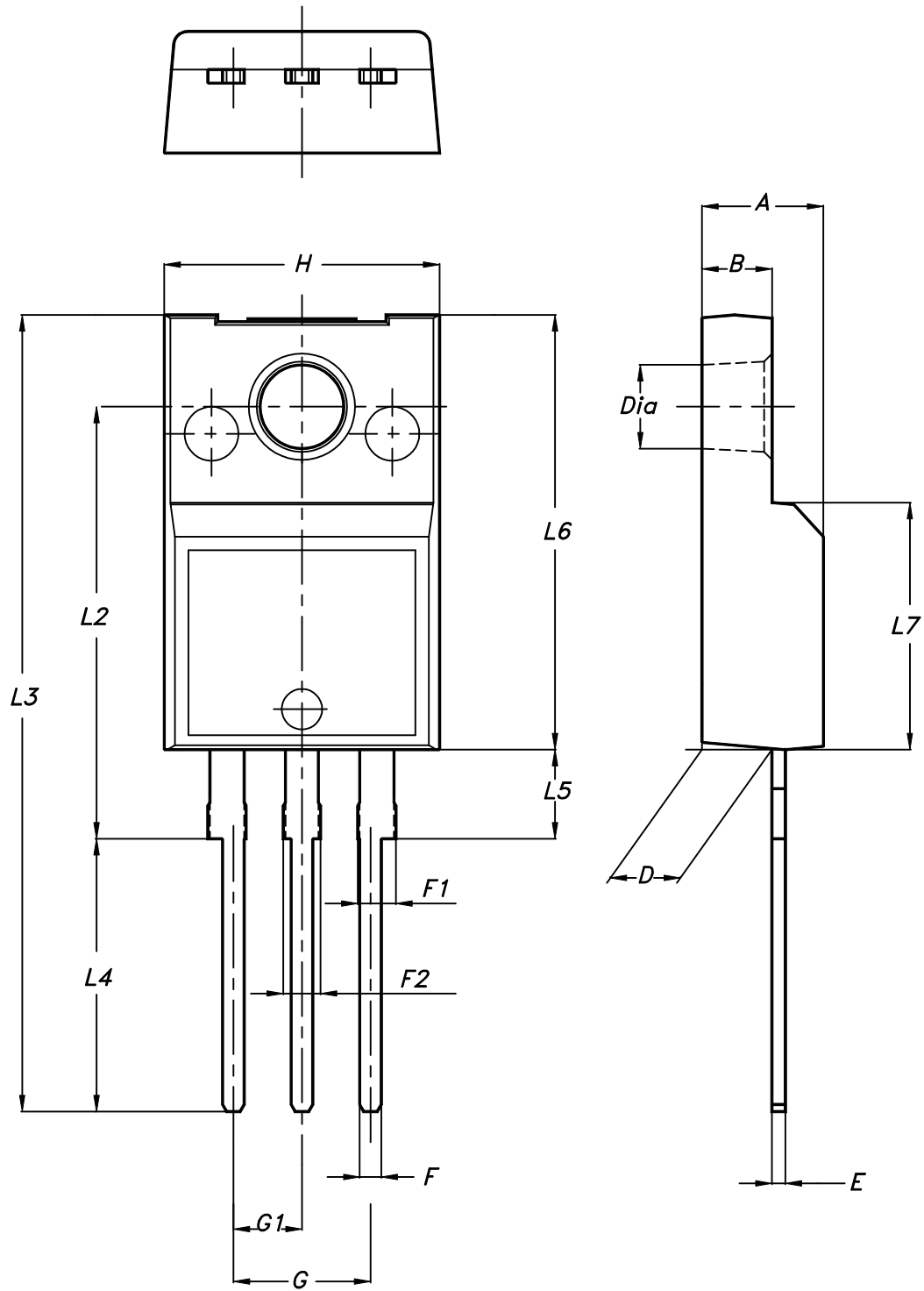
0015988\_typeA\_Rev\_21

**Table 13. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

4.6 TO-220FP package information

Figure 28. TO-220FP package outline



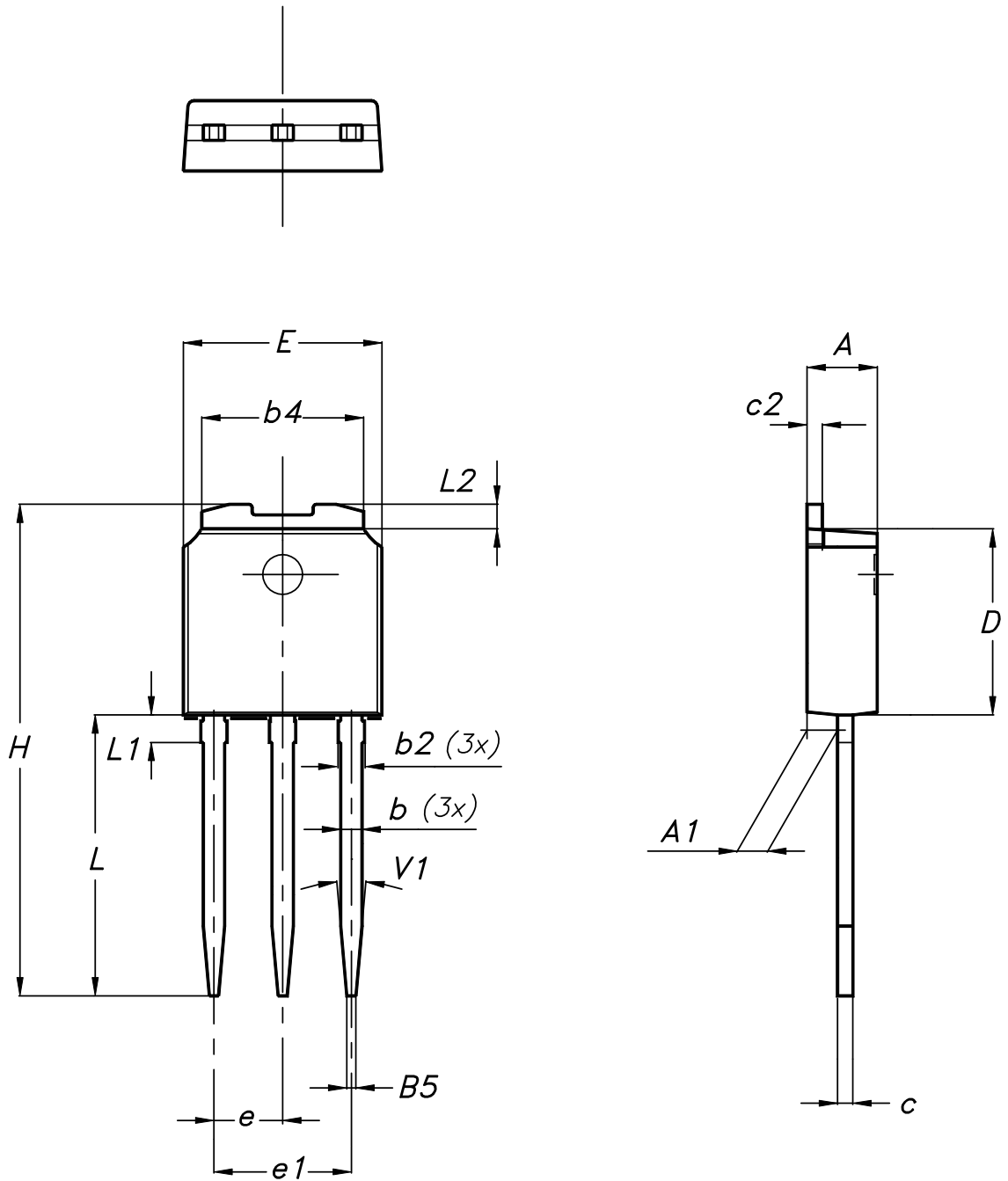
7012510\_Rev\_12\_B

**Table 14. TO-220FP package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

#### 4.7 IPAk (TO-251) type A package information

Figure 29. IPAk (TO-251) type A package outline



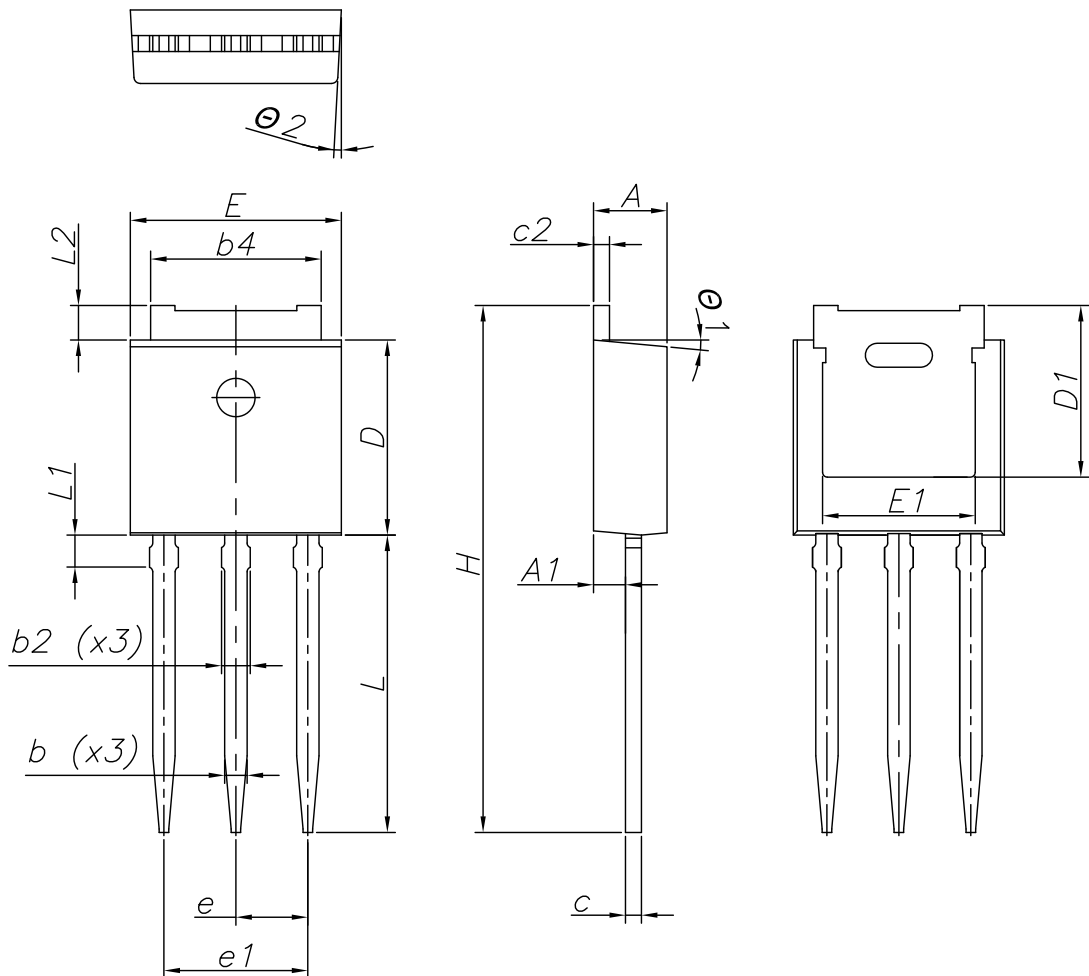
0068771\_IK\_typeA\_rev14

**Table 15. IPAK (TO-251) type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

#### 4.8 IPAK (TO-251) type C package information

Figure 30. IPAK (TO-251) type C package outline



0068771\_IK\_typeC\_rev14



**Table 16. IPAK (TO-251) type C package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.35
A1	0.90	1.00	1.10
b	0.66		0.79
b2			0.90
b4	5.23	5.33	5.43
c	0.46		0.59
c2	0.46		0.59
D	6.00	6.10	6.20
D1	5.20	5.37	5.55
E	6.50	6.60	6.70
E1	4.60	4.78	4.95
e	2.20	2.25	2.30
e1	4.40	4.50	4.60
H	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.80	1.00	1.20
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°

## 5 Ordering information

Table 17. Order codes

Order code	Marking	Package	Packing
STB5NK50Z-1	B5NK50Z	I <sup>2</sup> PAK	Tube
STD5NK50ZT4	D5NK50Z	DPAK	Tape and reel
STP5NK50Z	P5NK50Z	TO-220	Tube
STP5NK50ZFP	P5NK50ZFP	TO-220FP	Tube
STU5NK50Z	5NK50Z	IPAK	Tube

## Revision history

**Table 18. Document revision history**

Date	Version	Changes
16-Jun-2004	4	D <sup>2</sup> PAK Included. New Stylesheet.
06-Sep-2005	5	Inserted Ecopack indication
18-Sep-2018	6	The part number STB5NK50Z has been moved to a separate datasheet. Added part number STU5NK50Z. Updated <a href="#">Section 4 Package information</a> .

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